

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
	Name	Execution Date
	SEIKO INSTRUMENTS INC	02/01/2016
RECEIVING PARTY DATA		
Name:	SII SEMICONDUCTOR CORPORATION	
Street Address:	8, NAKASE 1-CHOME, MIHAMA-KU	
City:	CHIBA-SHI, CHIBA	
State/Country:	JAPAN	
Postal Code:	261-8507	
PROPERTY NUMBERS Total: 1		
	Property Type	Number
	Application Number:	13871380
CORRESPONDENCE DATA		
Fax Number:	(312)321-4299	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>		
Phone:	312-321-4200	
Email:	hkakiuchi@brinksgilson.com, usassignments@brinksgilson.com	
Correspondent Name:	TADASHI HORIE/HISAMI KAKIUCHI	
Address Line 1:	P.O. BOX 10395	
Address Line 4:	CHICAGO, ILLINOIS 60610	
ATTORNEY DOCKET NUMBER:	11106/620	
NAME OF SUBMITTER:	TADASHI HORIE	
SIGNATURE:	/Tadashi Horie/	
DATE SIGNED:	02/09/2016	
Total Attachments: 4		
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PATENT ASSIGNMENT AGREEMENT

This PATENT ASSIGNMENT AGREEMENT (this "Assignment") is entered into by and between Seiko Instruments Inc., a corporation organized and existing under the laws of Japan, having a place of business at 8, Nakase 1-chome, Mihama-ku, Chiba-shi, Chiba, Japan 261-8507, ("Assignor"), and SII Semiconductor Corporation, a corporation organized and existing under the laws of Japan, having a place of business at 8, Nakase 1-chome, Mihama-ku, Chiba-shi, Chiba, Japan 261-8507, ("Assignee") (each, a "Party," and collectively, the "Parties").

WHEREAS, Schedule A attached hereto identifies the patent jointly owned by Assignor and Ritsumeikan University (the "Patent"); and

WHEREAS, Assignor has agreed to assign to Assignee, and Assignee desires to receive from Assignor, all of Assignor's right, title and undivided interest in and to the Patent.

NOW, THEREFORE, in consideration of the premises and the mutual agreements and covenants hereinafter set forth, the Parties hereto agree as follows:

1. Assignment (a) Assignor hereby irrevocably assigns, transfers, conveys and delivers to Assignee, free and clear of any Encumbrances (other than Permitted Encumbrances), and Assignee hereby receives from Assignor, all of Assignor's right, title and undivided interest in and to the Patent for the United States and for all foreign countries, including, without limitation, the inventions and improvements described and claimed therein, all reissues, revisions, divisionals, continuations, extensions, continuations-in-part and counterparts thereof and all corresponding rights that are or may be secured under the laws of the United States or any foreign country, now or hereafter arising or in effect, for Assignee's own use and enjoyment, and for the use and enjoyment of Assignee's successors,

assigns and other legal representatives, as fully and entirely as the same would have been held and enjoyed by Assignor if this Assignment had not been made, together with Assignor's all rights to collect royalties, products and proceeds in connection with any of the foregoing and Assignor's all rights to sue and recover damages or other relief for all past, present or future infringement, misappropriation or other violation of any of the foregoing, and all rights corresponding thereto throughout the world.

(b) Assignor hereby requests the Commissioner of Patents and Trademarks in the United States Patent and Trademark Office, and the corresponding entities or agencies in any applicable foreign countries or multinational authorities, to record Assignee as the assignee and co-owner of the Patent and to deliver to Assignee, and to Assignee's attorneys, agents, successors or assigns, all official documents and communications as may be warranted by this Assignment.

(c) The Parties agree that this Assignment does not affect or alter the right, title and undivided interest of Ritsumeikan University in and to the Patent.

2. Further Action. Assignor and Assignee shall each take, and shall cause their respective Affiliates to take, any and all additional actions as may be necessary or appropriate to effect the transactions contemplated hereby, including, but not limited to, execution of individual assignment documentation for filing with the authorities of each individual country. The responsibility to file assignments with the national patent offices of each country shall be on the Assignee and the Assignee shall bear the cost of filing such assignments.

3. Counterparts. This Assignment may be executed and delivered (including by facsimile or other means of electronic transmission, such as by electronic mail in "pdf" form)

in one or more counterparts, and by the different Parties hereto in separate counterparts, each of which when executed shall be deemed to be an original, but all of which taken together shall constitute one and the same agreement.

4. Governing Law. This Assignment shall be governed by, and construed in accordance with, the Laws of Japan.

IN WITNESS THEREOF, the Parties hereto have caused this Assignment to be executed as of the date last written below by their respective officers thereunto duly authorized.

Seiko Instruments Inc.

By 

Name Toshihiko Sakuhara

Title General Manager

Date 2016/02/01

SII Semiconductor Corporation

By 

Name Nobumasa Ishiai

Title President & Representative Director

Date 2016/02/01

Schedule A

Application No.	SI Ref. No.	BGL No.	Title
13/871,380	12P00726	11106-620	ELECTRONIC DEVICE